INTEGRATED CIRCUITS

DATA SHEET

74ABT623

Octal transceiver with dual enable, non-inverting; (3-State)

Product specification Supersedes data of 1996 Sep 25 IC23 Data Handbook







Philips Semiconductors Product specification

Octal transceiver with dual enable, non-inverting (3-State)

74ABT623

FEATURES

- Octal bidirectional bus interface
- 3-State buffers
- Power-up 3-State
- Output capability: +64mA/-32mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Inputs are disabled during 3-State mode

DESCRIPTION

The 74ABT623 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT623 device is an octal transceiver featuring non–inverting 3-State bus compatible outputs in both send and receive directions. The 74ABT623 is designed for asynchronous two-way communication between data buses. The control function implementation allows for maximum flexibility in timing. This device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic levels at the Enable inputs (OEBA and OEAB). The Enable inputs can be used to disable the device so that the buses are effectively isolated.

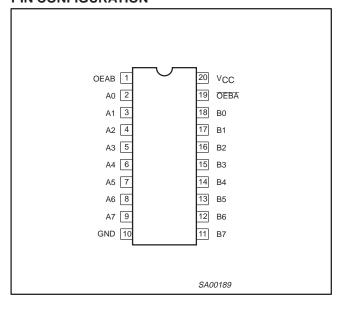
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay An to Bn or Bn to An	$C_L = 50pF; V_{CC} = 5V$	2.6 2.7	ns
C _{IN}	Input capacitance OEAB, OEBA	$V_I = 0V$ or V_{CC}	4	pF
C _{I/O}	I/O capacitance	Outputs disabled; $V_O = 0V$ or V_{CC}	7	pF
I _{CCZ}	Total supply current	Outputs disabled; V _{CC} =5.5V	50	μΑ

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic DIP	-40°C to +85°C	74ABT623 N	74ABT623 N	SOT146-1
20-Pin plastic SO	-40°C to +85°C	74ABT623 D	74ABT623 D	SOT163-1
20-Pin Plastic SSOP Type II	-40°C to +85°C	74ABT623 DB	74ABT623 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +85°C	74ABT623 PW	74ABT623PW DH	SOT360-1

PIN CONFIGURATION



PIN DESCRIPTION

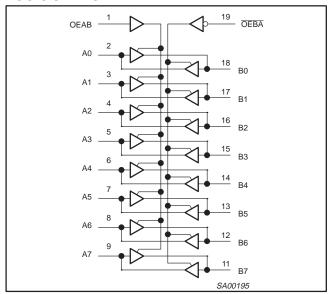
PIN NUMBER	SYMBOL	NAME AND FUNCTION
1	OEAB	Output enable input, A side to B side (active-High)
2, 3, 4, 5, 6, 7, 8, 9	A0 – A7	Data inputs/outputs (A side)
18, 17, 16, 15, 14, 13, 12, 11	B0 – B7	Data inputs/outputs (B side)
19	OEBA	Output enable input, B side to A side (active-Low)
10	GND	Ground (0V)
20	V _{CC}	Positive supply voltage

Philips Semiconductors Product specification

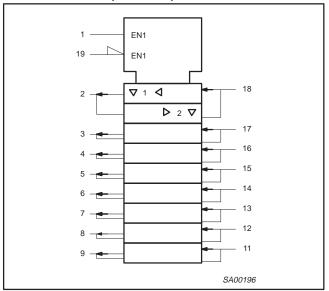
Octal transceiver with dual enable, non-inverting (3-State)

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LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

INP	JTS	INPUTS/OUTPUTS					
OEBA	OEAB	An	Bn				
L	L	An = Bn	Inputs				
Н	Н	Inputs	Bn = An				
Н	L	Z	Z				
L	Н	An = Bn	Bn = An				

- H = High voltage level
- _ = Low voltage level
- Z = High impedance "off" state

ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V _I < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
lok	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V
I _{OUT}	DC output current	output in Low state	128	mA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES:

- 1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
- 3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	ITS	UNIT
		Min	Max	
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Low-level input voltage		0.8	V
I _{OH}	High-level output current		-32	mA
I _{OL}	Low-level output current		64	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

DC ELECTRICAL CHARACTERISTICS

						LIMITS					
SYMBOL	SYMBOL PARAMETER		TEST CONDITIONS	Tai	_{mb} = +25	°C		: –40°C 85°C	UNIT		
				Min	Тур	Max	Min	Max			
V _{IK}	Input clamp volt		-0.9	-1.2		-1.2	V				
			$V_{CC} = 4.5V$; $I_{OH} = -3mA$; $V_I = V_{IL}$ or V_{IH}	2.5	2.9		2.5		V		
V_{OH}			$V_{CC} = 5.0V$; $I_{OH} = -3mA$; $V_I = V_{IL}$ or V_{IH}	3.0	3.4		3.0		V		
			$V_{CC} = 4.5V$; $I_{OH} = -32mA$; $V_I = V_{IL}$ or V_{IH}	2.0	2.4		2.0		V		
V _{OL}	Low-level output voltage		$V_{CC} = 4.5V$; $I_{OL} = 64mA$; $V_I = V_{IL}$ or V_{IH}		0.42	0.55		0.55	V		
II	Input leakage Control pins		V _{CC} = 5.5V; V _I = GND or 5.5V		±0.01	±1.0		±1.0	μΑ		
	current Data pins		current Data pins $V_{CC} = 5.5V$; $V_I = GND$ or $5.5V$					±100		±100	μΑ
I _{OFF}	Power-off leakage current		$V_{CC} = 0.0V; V_{I} \text{ or } V_{O} \le 4.5V$		±5.0	±100		±100	μΑ		
I _{PU} / _{IPD}	Power-up/down 3-State output current ³		V_{CC} = 2.0V; V_O = 0.5V; V_I = GND or V_{CC} ; V_{OE} = V_{CC} ; V_{OE} = GND		±5.0	±50		±50	μА		
I _{IH} + I _{OZH}	3-State output H	High current	$V_{CC} = 5.5V$; $V_O = 2.7V$; $V_I = V_{IL}$ or V_{IH}		5.0	50		50	μΑ		
I _{IL} + I _{OZL}	3-State output L	ow current	$V_{CC} = 5.5V$; $V_O = 0.5V$; $V_I = V_{IL}$ or V_{IH}		-5.0	-50		-50	μΑ		
I _{CEX}	Output High lea	kage current	V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = GND or V_{CC}		5.0	50		50	μΑ		
I _O	Output current ¹		$V_{CC} = 5.5V; V_{O} = 2.5V$	-50	-100	-180	-50	-180	mA		
I _{CCH}			$V_{CC} = 5.5V$; Outputs High, $V_{I} = GND$ or V_{CC}		50	250		250	μΑ		
I _{CCL}	Quiescent supp	ly current	$V_{CC} = 5.5V$; Outputs Low, $V_I = GND$ or V_{CC}		24	30		30	mA		
I _{CCZ}]		V_{CC} = 5.5V; Outputs 3-State; V_{I} = GND or V_{CC}		50	250		50	μΑ		
			Outputs enabled, one data input at 3.4V, other inputs at V_{CC} or GND; V_{CC} = 5.5V		0.5	1.5		1.5	mA		
ΔI _{CC} Additional supply current per input pin ²		ly current per	Outputs 3-State, one data input at 3.4V, other inputs at V_{CC} or GND; V_{CC} = 5.5V		50	250		250	μА		
			Outputs 3-State, one enable input at 3.4V, other inputs at V_{CC} or GND; V_{CC} = 5.5V		0.5	1.5		1.5	mA		

NOTES:

- 1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- 2. This is the increase in supply current for each input at 3.4V.
- 3. This parameter is valid for any V_{CC} between 0V and 2.1V with a transition time of up to 10msec. For V_{CC} = 2.1V to V_{CC} = 5V \pm 10%, a transition time of up to 100 μ sec is permitted.

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AC CHARACTERISTICS

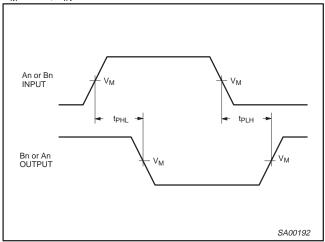
GND = 0V; $t_R = t_F = 2.5 \text{ns}$; $C_L = 50 \text{pF}$, $R_L = 500 \Omega$

SYMBOL	PARAMETER	WAVEFORM	T ₂	_{amb} = +25° ' _{CC} = +5.0'	C V	T _{amb} = -40° V _{CC} = +5.	UNIT	
			Min	Тур	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation delay An to Bn or Bn to An	1	1.0 1.0	2.6 2.7	4.1 4.2	1.0 1.0	4.6 4.6	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level	2	1.7 1.7	3.4 4.8	6.5 6.5	1.7 1.7	7.5 7.5	ns
t _{PHZ}	Output disable time to High and Low level	2	1.7 1.7	3.6 3.1	6.5 6.5	1.7 1.7	7.5 7.5	ns

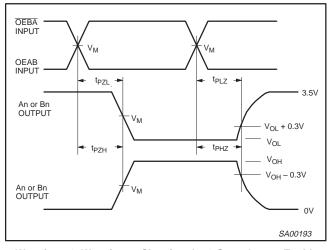
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AC WAVEFORMS

 $V_M = 1.5V$, $V_{IN} = GND$ to 3.0V

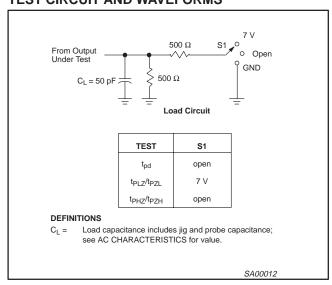


Waveform 1. Waveforms Showing the Input to Output Propagation Delays



Waveform 2. Waveforms Showing the 3-State Output Enable and Disable Times

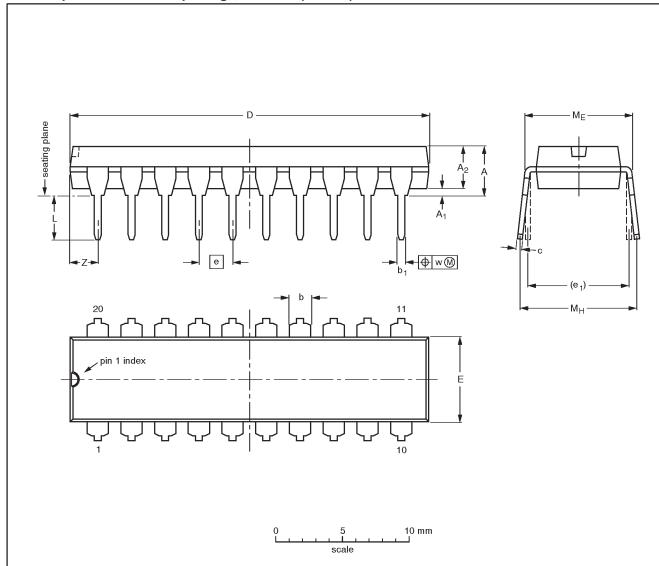
TEST CIRCUIT AND WAVEFORMS



74ABT623

DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	Мн	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

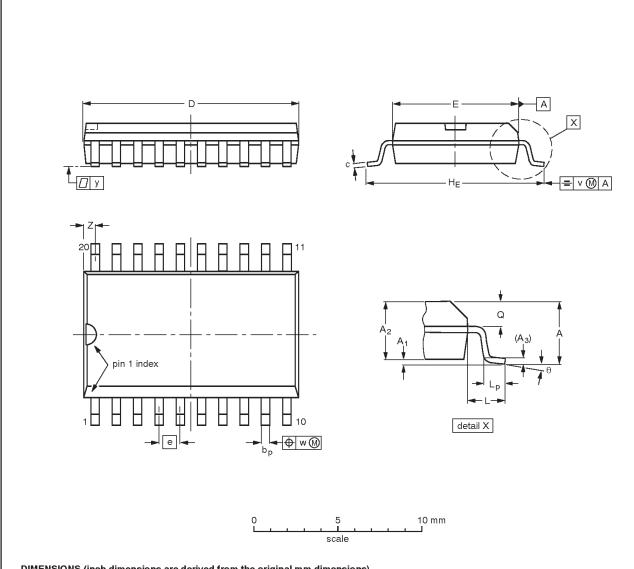
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ	PROJECTION		
SOT146-1			SC603		-92-11-17 95-05-24	

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74ABT623

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bp	O	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	٧	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	0°

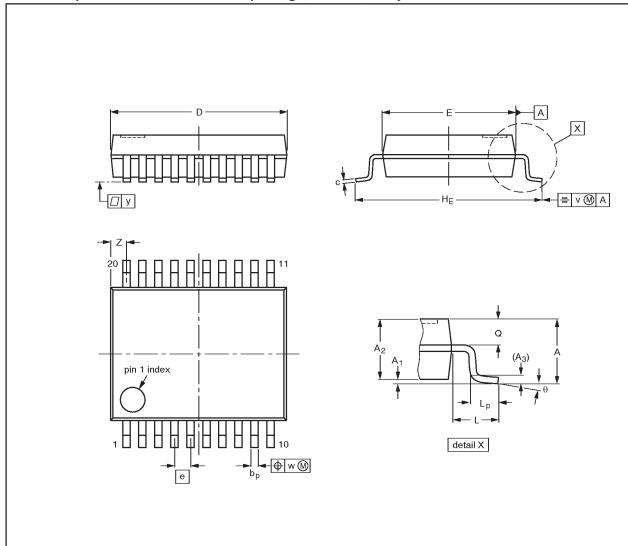
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC JEDEC		EIAJ	PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC			-92-11-17 95-01-24	

74ABT623

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bр	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Ø	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Note

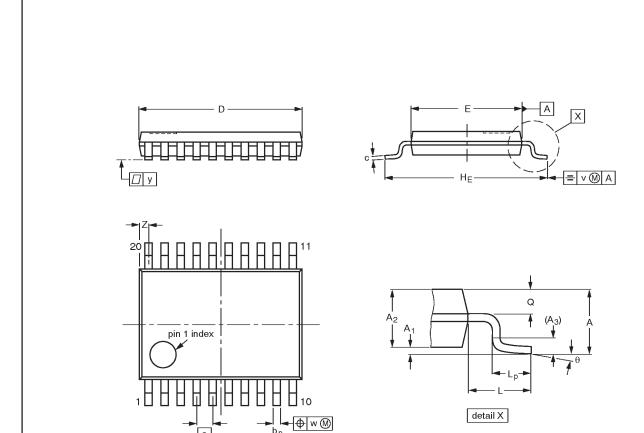
1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

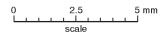
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT339-1		MO-150AE			93-09-08 95-02-04

74ABT623

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	рb	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUEDATE
SOT360-1		MO-153AC			-93-06-16 95-02-04

Philips Semiconductors Product specification

Octal transceiver with dual enable, non-inverting (3-State)

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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